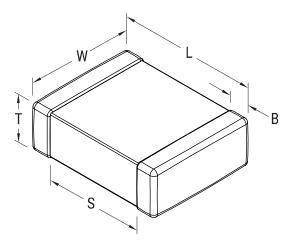


## C1206X103F3GECTU

Aliases (C1206X103F3GEC7800) ESD SMD Comm C0G, Ceramic, 0.01 uF, 1%, 25 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
S	1.5mm MIN

## **Packaging Specifications**

Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.